

High-speed double diode**BAS28****FEATURES**

- Small plastic SMD package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 85 V
- Repetitive peak forward current: max. 500 mA .

APPLICATIONS

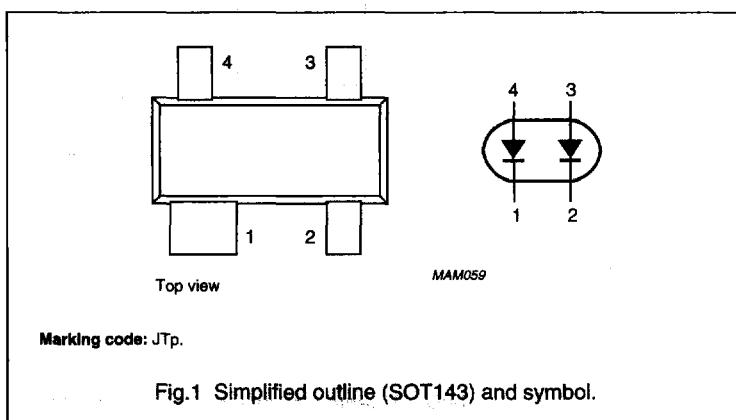
- High-speed switching in e.g. surface mounted circuits.

DESCRIPTION

The BAS28 consists of two high-speed switching diodes, fabricated in planar technology, and encapsulated in the small plastic SMD SOT143 package. The diodes are not connected.

PINNING

PIN	DESCRIPTION
1	cathode (k1)
2	cathode (k2)
3	anode (a2)
4	anode (a1)

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		—	85	V
V_R	continuous reverse voltage		—	75	V
I_F	continuous forward current	see Fig.2; note 1	—	215	mA
I_{FRM}	repetitive peak forward current		—	500	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25^\circ\text{C}$ prior to surge; see Fig.4 $t = 1 \mu\text{s}$ $t = 1 \text{ ms}$ $t = 1 \text{ s}$	— — —	4 1 0.5	A
P_{tot}	total power dissipation	$T_{amb} = 25^\circ\text{C}$; note 1	—	250	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		—	150	°C

Note

1. Device mounted on an FR4 printed-circuit board.

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ELECTRICAL CHARACTERISTICS $T_j = 25^\circ\text{C}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_F	forward voltage	see Fig.3 $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 50 \text{ mA}$ $I_F = 150 \text{ mA}$	— — — —	715 855 1 1.25	mV mV V V
I_R	reverse current	see Fig.5 $V_R = 25 \text{ V}$ $V_R = 75 \text{ V}$ $V_R = 25 \text{ V}; T_j = 150^\circ\text{C}$ $V_R = 75 \text{ V}; T_j = 150^\circ\text{C}$	— — — —	30 1 30 50	nA μA μA μA
C_d	diode capacitance	$f = 1 \text{ MHz}; V_R = 0$; see Fig.6	—	1.5	pF
t_{rr}	reverse recovery time	when switched from $I_F = 10 \text{ mA}$ to $I_R = 10 \text{ mA}$; $R_L = 100 \Omega$; measured at $I_R = 1 \text{ mA}$; see Fig.7	—	4	ns
V_{fr}	forward recovery voltage	when switched from $I_F = 10 \text{ mA}$; $t_r = 20 \text{ ns}$; see Fig.8	—	1.75	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th j\text{-tp}}$	thermal resistance from junction to tie-point		360	K/W
$R_{th j\text{-a}}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Device mounted on an FR4 printed-circuit board.

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GRAPHICAL DATA

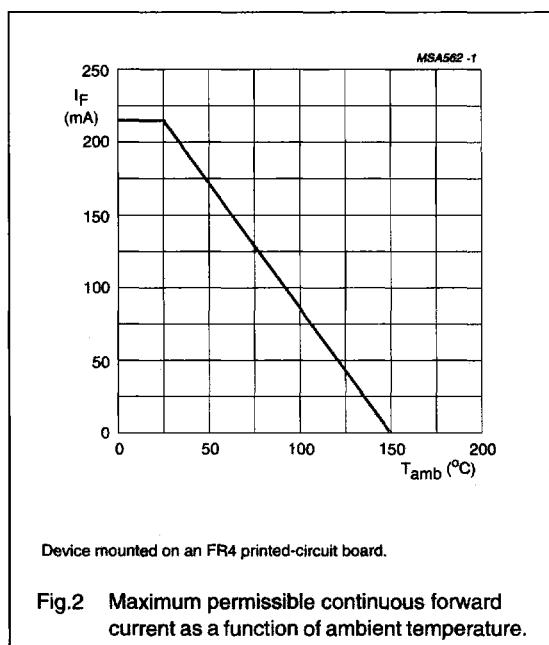


Fig.2 Maximum permissible continuous forward current as a function of ambient temperature.

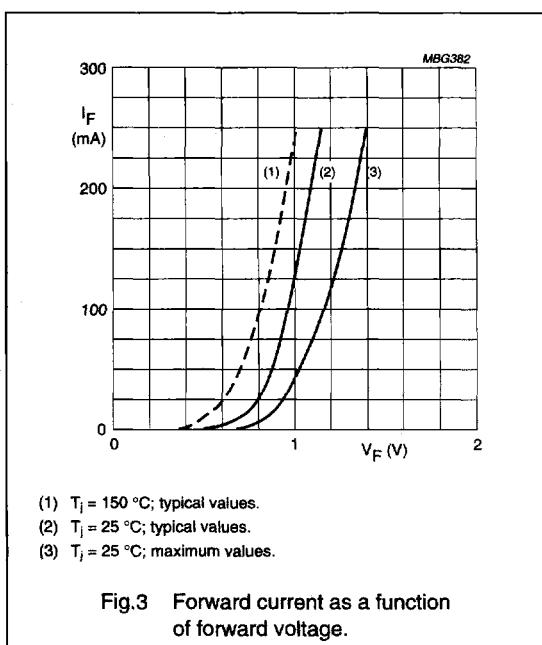


Fig.3 Forward current as a function of forward voltage.

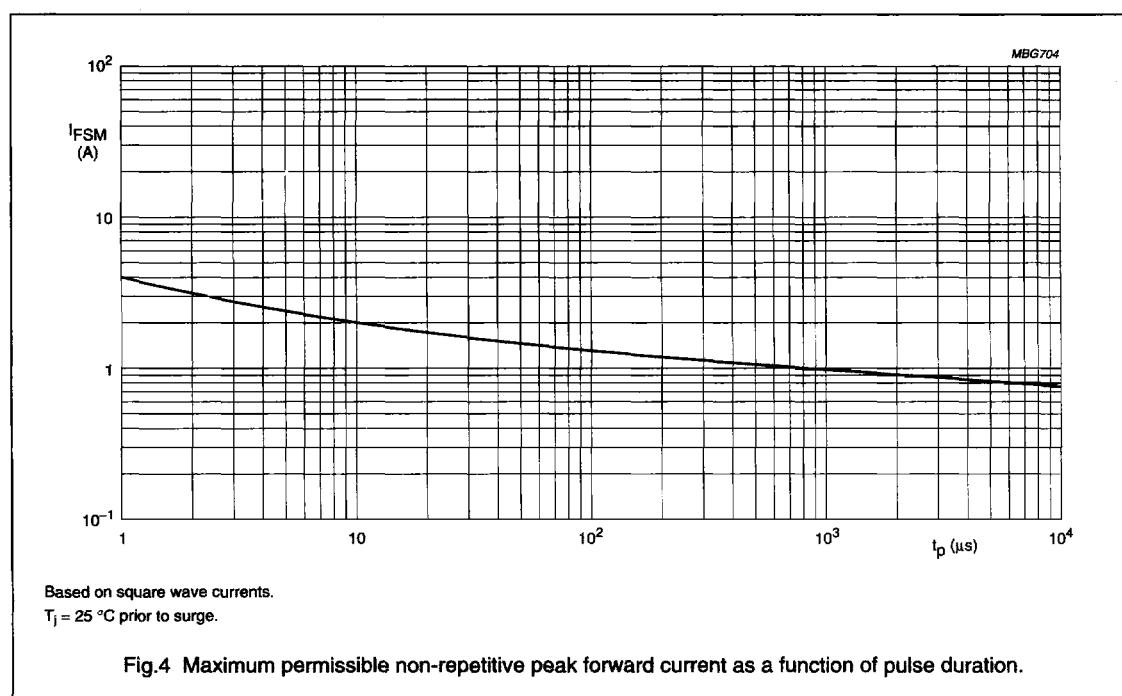


Fig.4 Maximum permissible non-repetitive peak forward current as a function of pulse duration.

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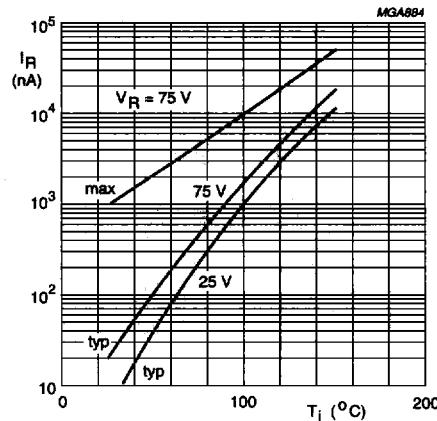
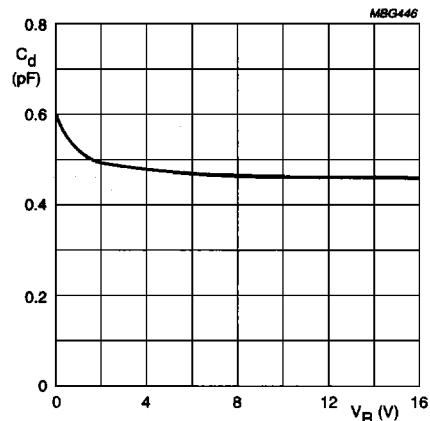


Fig.5 Reverse current as a function of junction temperature.



$f = 1$ MHz; $T_j = 25$ °C.

Fig.6 Diode capacitance as a function of reverse voltage; typical values.

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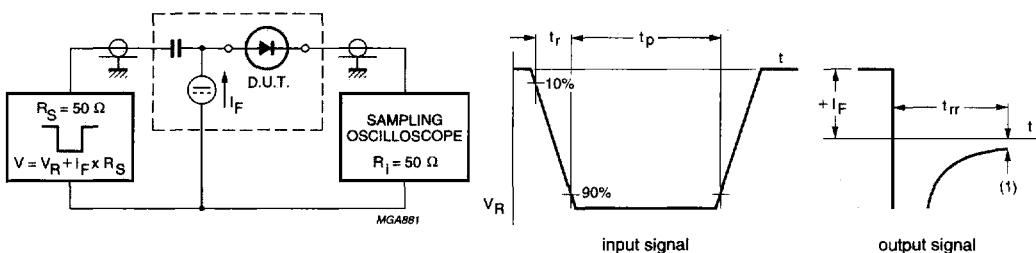


Fig. 7 Reverse recovery voltage test circuit and waveforms.

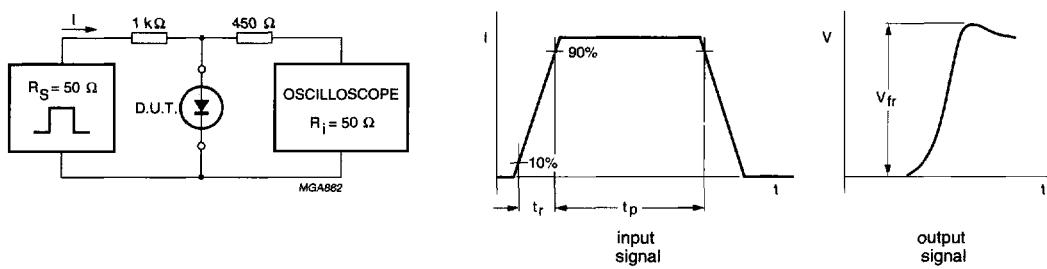


Fig. 8 Forward recovery voltage test circuit and waveforms.